

Pin Configurations

Figure 1. Pin Diagram - DIP (Top View)

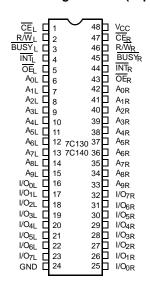


Figure 2. Pin Diagram - PLCC (Top View)

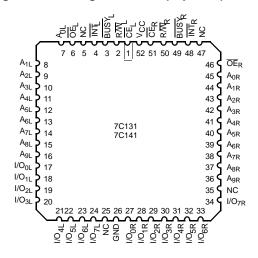
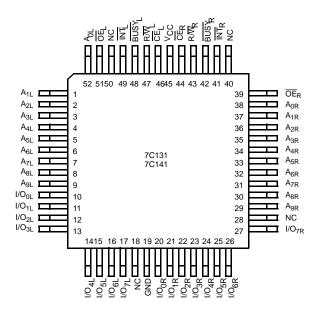


Figure 3. Pin Diagram - PQFP (Top View)





Pin Definitions

Left Port	Right Port	Description
CEL	CER	Chip Enable
R/\overline{W}_L	R/W _R	Read/Write Enable
OEL	OE _R	Output Enable
A _{0L} -A _{11/12L}	A _{0R} -A _{11/12R}	Address
I/O _{0L} -I/O _{15/17L}	I/O _{0R} -I/O _{15/17R}	Data Bus Input/Output
INT _L	INT _R	Interrupt Flag
BUSY _L	BUSY _R	Busy Flag
V _{CC}		Power
GND		Ground

Selection Guide

Parameter		7C131-15 ^[4] 7C131A-15 7C141-15	7C131-25 ^[4] 7C141-25	7C130-30 7C130A-30 7C131-30 7C140-30 7C141-30	7C130-35 7C131-35 7C140-35 7C141-35	7C130-45 7C131-45 7C140-45 7C141-45	7C130-55 7C131-55 7C140-55 7C141-55	Unit
Maximum Access Time		15	25	30	35	45	55	ns
Maximum Operating Current	Com'l/Ind	190	170	170	120	120	110	mA
Maximum Standby Current	Com'l/Ind	75	65	65	45	45	35	mA

Shaded areas contain preliminary information.

Note
4. 15 and 25 ns version available only in PLCC/PQFP packages.



Maximum Ratings^[5]

Exceeding maximum ratings may shorten the useful life of the device. User guidelines are not tested.

Storage Temperature-65°C to +150°C Ambient Temperature with Power Applied -55°C to +125°C Supply Voltage to Ground Potential (Pin 48 to Pin 24).....-0.5V to +7.0V DC Voltage Applied to Outputs in High Z State-0.5V to +7.0V

DC Input Voltage	3.5V to +7.0V
Output Current into Outputs (LOW)	20 mA
Static Discharge Voltage(per MIL-STD-883, Method 3015)	>2001V
Latch Up Current	>200 mA

Operating Range

Range	Ambient Temperature	V _{CC}
Commercial	0°C to +70°C	5V ± 10%
Industrial	-40°C to +85°C	5V ± 10%
Military ^[6]	−55°C to +125°C	5V ± 10%

Electrical Characteristics Over the Operating Range^[7]

Parameter	Description	Test Conditions		7C13	1-15 ^[4] 1A-15 41-15	7C13 7C131 7C14	0-30 ^[4] 0A-30 1-25,30 40-30 1-25,30	7C13 ² 7C140	0-35,45 1-35,45 0-35,45 1-35,45	7C13	80-55 81-55 10-55 11-55	Unit
				Min	Max	Min	Max	Min	Max	Min	Max	
V _{OH}	Output HIGH Voltage	$V_{CC} = Min, I_{OH} = -4.0 \text{ mA}$		2.4		2.4		2.4		2.4		V
V_{OL}	Output LOW Voltage	$I_{OL} = 4.0 \text{ mA}$			0.4		0.4		0.4		0.4	V
		$I_{OL} = 16.0 \text{ mA}^{[8]}$			0.5		0.5		0.5		0.5	
V _{IH}	Input HIGH Voltage			2.2		2.2		2.2		2.2		V
V_{IL}	Input LOW Voltage				0.8		0.8		0.8		0.8	V
I _{IX}	Input Leakage Current	$GND \leq V_1 \leq V_{CC}$		-5	+5	-5	+5	- 5	+5	-5	+5	μА
I _{OZ}	Output Leakage Current	$\begin{array}{l} \text{GND} \leq \text{V}_{\text{O}} \leq \text{V}_{\text{CC}}, \\ \text{Output Disabled} \end{array}$		- 5	+5	- 5	+5	- 5	+5	– 5	+5	μА
I _{OS}	Output Short Circuit Current ^[9, 10]	V_{CC} = Max, V_{OUT} = GND			-350		-350		-350		-350	mA
I _{CC}	V _{CC} Operating Supply Current	$CE = V_{IL}$, Outputs Open, $f = f_{MAX}^{[11]}$	Com'l		190		170		120		110	mA
I _{SB1}	Standby Current Both Ports, TTL Inputs	CE_L and $CE_R \ge V_{IH}$, $f = f_{MAX}^{[11]}$	Com'l		75		65		45		35	mA
I _{SB2}	Standby Current One Port, TTL Inputs	CE_L or $CE_R \ge V_{IH}$, Active Port Outputs Open $f = f_{MAX}^{[11]}$	Com'l		135		115		90		75	mA
I _{SB3}	Standby Current Both Ports, CMOS Inputs	Both Ports CE_L and $CE_R \ge V_{CC} - 0.2V$, $V_{IN} \ge V_{CC} - 0.2V$ or $V_{IN} \le 0.2V$, $f = 0$	Com'l		15		15		15		15	mA
I _{SB4}	Standby Current One Port, CMOS Inputs	$\begin{array}{l} \underline{\text{One}} \; \text{Port} \; \text{CE}_L \; \text{or} \\ \text{CE}_R \geq \text{V}_{\text{CC}} - 0.2\text{V}, \\ \text{V}_{\text{IN}} \geq \text{V}_{\text{CC}} - 0.2\text{V} \\ \text{or} \; \text{V}_{\text{IN}} \leq 0.2\text{V}, \\ \text{Active} \; \text{Port} \; \text{Outputs} \; \text{Open, f} = f_{\text{MAX}}^{[11]} \end{array}$	Com'I		125		105		85		70	mA

Shaded areas contain preliminary information.

Notes

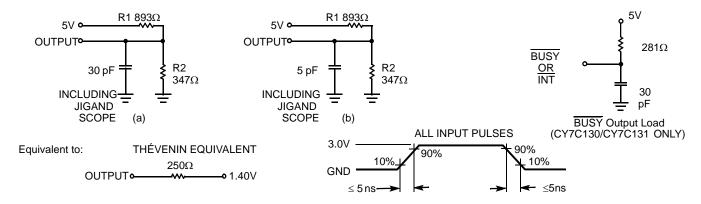
- 5. The voltage on any input or I/O pin cannot exceed the power pin during power up.
- 6. T_A is the "instant on" case temperature
- See the last page of this specification for Group A subgroup testing information.
 BUSY and INT pins only.
- 9. Duration of the short circuit should not exceed 30 seconds.
- 10. This parameter is guaranteed but not tested.
- 11. At f = f_{MAX}, address and data inputs are cycling at the maximum frequency of read cycle of 1/t_{RC} and using AC Test Waveforms input levels of GND to 3V.



Capacitance^[10]

Parameter	Description	Test Conditions	Max	Unit
C _{IN}	Input Capacitance	$T_A = 25^{\circ}C$, f = 1 MHz,	15	pF
C _{OUT}	Output Capacitance	$V_{CC} = 5.0V$	10	pF

Figure 4. AC Test Loads and Waveforms





Switching Characteristics Over the Operating Range^[7, 12]

Parameter	Description	7C13	1-15 ^[4] 1A-15 11-15	7C1: 7C1	0-25 ^[4] 31-25 40-25 41-25	7C13 7C13 7C14	30-30 0A-30 31-30 40-30 41-30	Unit
		Min	Max	Min	Max	Min	Max	
Read Cycle								
t _{RC}	Read Cycle Time	15		25		30		ns
t _{AA}	Address to Data Valid ^[13]		15		25		30	ns
t _{OHA}	Data Hold from Address Change	0		0		0		ns
t _{ACE}	CE LOW to Data Valid ^[13]		15		25		30	ns
t _{DOE}	OE LOW to Data Valid ^[13]		10		15		20	ns
t _{LZOE}	OE LOW to Low Z ^[10, 14, 15]	3		3		3		ns
t _{HZOE}	OE HIGH to High Z ^[10, 14, 15]		10		15		15	ns
t _{LZCE}	CE LOW to Low Z ^[10, 14, 15]	3		5		5		ns
t _{HZCE}	CE HIGH to High Z ^[10, 14, 15]		10		15		15	ns
t _{PU}	CE LOW to Power Up ^[10]	0		0		0		ns
t _{PD}	CE HIGH to Power Down ^[10]		15		25		25	ns
Write Cycle	16]			I		I	ı	1
t _{WC}	Write Cycle Time	15		25		30		ns
t _{SCE}	CE LOW to Write End	12		20		25		ns
t _{AW}	Address Setup to Write End	12		20		25		ns
t _{HA}	Address Hold from Write End	2		2		2		ns
t _{SA}	Address Setup to Write Start	0		0		0		ns
t _{PWE}	R/W Pulse Width	12		15		25		ns
t _{SD}	Data Setup to Write End	10		15		15		ns
t _{HD}	Data Hold from Write End	0		0		0		ns
t _{HZWE}	R/W LOW to High Z ^[15]		10		15		15	ns
t _{LZWE}	R/W HIGH to Low Z ^[15]	0		0		0		ns
	Itain preliminary information.		1	ı	1	l	1	1

Notes

<sup>Notes
12. Test conditions assume signal transition times of 5 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V and output loading of the specified loL/loH, and 30 pF load capacitance.
13. AC Test Conditions use VOH = 1.6V and VOL = 1.4V.
14. At any given temperature and voltage condition for any given device, tHZCE is less than tLZCE and tHZOE is less than tLZOE.
15. tLZCE, tLZWE, tHZOE, tLZOE, tHZCE and tHZWE are tested with CL = 5 pF as in part (b) of AC Test Loads. Transition is measured ±500 mV from steady state voltage.
16. The internal write time of the memory is defined by the overlap of CS LOW and R/W LOW. Both signals must be low to initiate a write and either signal can terminate a write by going high. The data input setup and hold timing should be referenced to the rising edge of the signal that terminates the write.</sup>



Switching Characteristics Over the Operating Range^[7, 12] (continued)

		1A-15 41-15		40-25 41-25	7C14	31-30 40-30 41-30	Unit
	Min	Max	Min	Max	Min	Max	
ng							
LOW from Address Match		15		20		20	ns
HIGH from Address Mismatch ^[17]		15		20		20	ns
LOW from CE LOW		15		20		20	ns
HIGH from CE HIGH ^[17]		15		20		20	ns
et Up for Priority	5		5		5		ns
DW after BUSY LOW	0		0		0		ns
GH after BUSY HIGH	13		20		30		ns
HIGH to Valid Data		15		25		30	ns
Data Valid to Read Data Valid		Note 19		Note 19		Note 19	ns
Pulse to Data Delay		Note 19		Note 19		Note 19	ns
				•			
INTERRUPT Set Time		15		25		25	ns
NTERRUPT Set Time		15		25		25	ns
s to INTERRUPT Set Time		15		25		25	ns
NTERRUPT Reset Time ^[17]		15		25		25	ns
NTERRUPT Reset Time ^[17]		15		25		25	ns
s to INTERRUPT Reset Time ^[17]		15		25		25	ns
	LOW from Address Match HIGH from Address Mismatch ^[17] LOW from CE LOW HIGH from CE HIGH ^[17] et Up for Priority DW after BUSY LOW GH after BUSY HIGH HIGH to Valid Data Pata Valid to Read Data Valid Pulse to Data Delay INTERRUPT Set Time NTERRUPT Reset Time NTERRUPT Reset Time ^[17]	LOW from Address Match HIGH from Address Mismatch [17] LOW from CE LOW HIGH from CE HIGH [17] et Up for Priority OW after BUSY LOW GH after BUSY HIGH 13 HIGH to Valid Data Pata Valid to Read Data Valid Pulse to Data Delay INTERRUPT Set Time Sto INTERRUPT Set Time NTERRUPT Reset Time [17] NTERRUPT Reset Time [17]	LOW from Address Match 15 HIGH from Address Mismatch ^[17] 15 LOW from CE LOW 15 HIGH from CE HIGH ^[17] 15 et Up for Priority 5 DW after BUSY LOW 0 GH after BUSY HIGH 13 HIGH to Valid Data 15 Data Valid to Read Data Valid Note 19 Pulse to Data Delay Note 19 INTERRUPT Set Time 15 S to INTERRUPT Set Time 15 NTERRUPT Reset Time ^[17] 15 NTERRUPT Reset Time ^[17] 15	LOW from Address Match 15 HIGH from Address Mismatch 15 LOW from CE LOW 15 HIGH from CE HIGH 17 15 Et Up for Priority 5 5 5 DW after BUSY LOW 0 0 0 GH after BUSY HIGH 13 20 HIGH to Valid Data 15 Data Valid to Read Data Valid Note 19 Evaluate to Data Delay Note 19 INTERRUPT Set Time 15 S to INTERRUPT Set Time 15 NTERRUPT Reset Time 15 NTERRUPT Reset Time 17] 15 NTERRUPT Reset Time 15 NTERRUPT Reset Time 15 NTERRUPT Reset Time 15	LOW from Address Match 15	Min Max Min Min	Min Max Min Max Min Max In Max Min Max Min Max In In In In In In In

Shaded areas contain preliminary information.

Notes

^{17.} These parameters are measured from the input signal changing, until the output pin goes to a high-impedance state. 18. CY7C140/CY7C141 only.

^{18.} A write operation on Port A, where Port A has priority, leaves the data on Port B's outputs undisturbed until one access time after one of the following: BUSY on Port B goes HIGH.

Port B's address is toggled.

CE for Port B is toggled.

RW for Port B is toggled during valid read.



$\textbf{Switching Characteristics} \ \ \text{Over the Operating Range}^{[7,12]}$

Parameter	Description	7C1 7C1	30-35 31-35 40-35 41-35	7C13	30-45 31-45 40-45 41-45	7C1 7C1	30-55 31-55 40-55 41-55	Unit
		Min	Max	Min	Max	Min	Max	
Read Cycle								
t _{RC}	Read Cycle Time	35		45		55		ns
t_{AA}	Address to Data Valid ^[13]		35		45		55	ns
t _{OHA}	Data Hold from Address Change	0		0		0		ns
t _{ACE}	CE LOW to Data Valid ^[13]		35		45		55	ns
t _{DOE}	OE LOW to Data Valid ^[13]		20		25		25	ns
t _{LZOE}	OE LOW to Low Z ^[10, 14, 15]	3		3		3		ns
t _{HZOE}	OE HIGH to High Z ^[10, 14, 15]		20		20		25	ns
t _{LZCE}	CE LOW to Low Z ^[10, 14, 15]	5		5		5		ns
t _{HZCE}	CE HIGH to High Z ^[10, 14, 15]		20		20		25	ns
t _{PU}	CE LOW to Power Up ^[10]	0		0		0		ns
t _{PD}	CE HIGH to Power Down ^[10]		35		35		35	ns
Write Cycle ^{[7}	16]							
t _{WC}	Write Cycle Time	35		45		55		ns
t _{SCE}	CE LOW to Write End	30		35		40		ns
t _{AW}	Address Setup to Write End	30		35		40		ns
t _{HA}	Address Hold from Write End	2		2		2		ns
t _{SA}	Address Setup to Write Start	0		0		0		ns
t _{PWE}	R/W Pulse Width	25		30		30		ns
t _{SD}	Data Setup to Write End	15		20		20		ns
t _{HD}	Data Hold from Write End	0		0		0		ns
t _{HZWE}	R/W LOW to High Z ^[15]		20		20		25	ns
t _{LZWE}	R/W HIGH to Low Z ^[15]	0		0		0		ns
Busy/Interru	pt Timing	•	•					
t _{BLA}	BUSY LOW from Address Match		20		25		30	ns
t _{BHA}	BUSY HIGH from Address Mismatch ^[17]		20		25		30	ns
t _{BLC}	BUSY LOW from CE LOW		20		25		30	ns
t _{BHC}	BUSY HIGH from CE HIGH ^[17]		20		25		30	ns
t _{PS}	Port Set Up for Priority	5		5		5		ns
t _{WB} ^[18]	R/W LOW after BUSY LOW	0		0		0		ns
t_{WH}	R/W HIGH after BUSY HIGH	30		35		35		ns
t _{BDD}	BUSY HIGH to Valid Data		35		45		45	ns
t _{DDD}	Write Data Valid to Read Data Valid		Note 19		Note 19		Note 19	ns
t _{WDD}	Write Pulse to Data Delay		Note 19		Note 19		Note 19	ns
Interrupt Tin	ning		1					
t _{WINS}	R/W to INTERRUPT Set Time		25		35		45	ns
t _{EINS}	CE to INTERRUPT Set Time		25		35		45	ns
t _{INS}	Address to INTERRUPT Set Time		25		35		45	ns
toinr	OE to INTERRUPT Reset Time ^[17]		25		35		45	ns
t _{EINR}	CE to INTERRUPT Reset Time ^[17]		25		35		45	ns
t _{INR}	Address to INTERRUPT Reset Time[17]		25		35		45	ns



Switching Waveforms

Figure 5. Read Cycle No. 1^[20, 21]

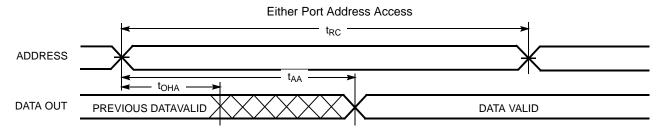


Figure 6. Read Cycle No. 2^[20, 22]

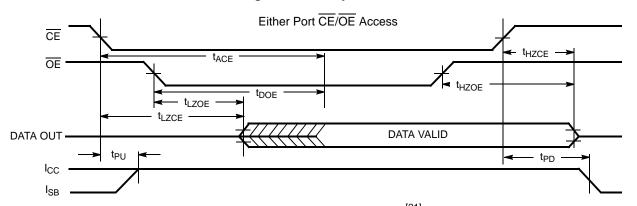
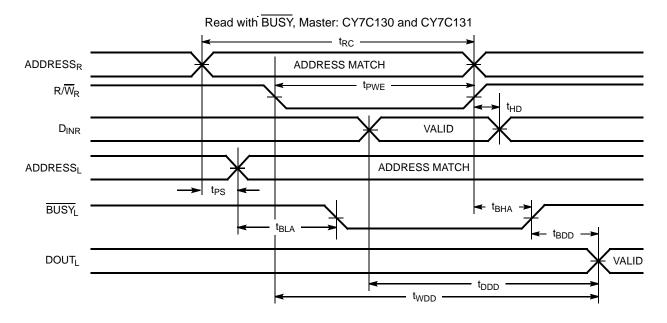


Figure 7. Read Cycle No. 3^[21]



- 20. R/W is HIGH for read cycle. 21. Device is continuously selected, $\overline{CE} = V_{\parallel}$ and $\overline{OE} = V_{\parallel}$. 22. Address valid prior to or coincident with \overline{CE} transition LOW.

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Figure 8. Write Cycle No. 1 (OE Three-States Data I/Os—Either Port[16, 23]

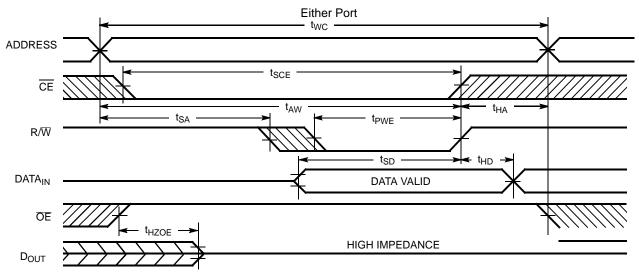
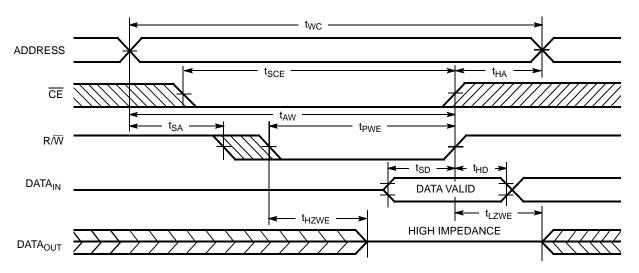


Figure 9. Write Cycle No. 2 (R/W Three-States Data I/Os—Either Port)[17, 24]



Notes

 ^{23.} If OE is LOW during a R\overline{W} controlled write cycle, the write pulse width must be the larger of t_{PWE} or t_{HZWE} + t_{SD} to allow the data I/O pins to enter high impedance and for data to be placed on the bus for the required t_{SD}.
 24. If the \overline{CE} LOW transition occurs simultaneously with or after the R\overline{W} LOW transition, the outputs remain in the high impedance state.



Figure 10. Busy Timing Diagram No. 1 (CE Arbitration)

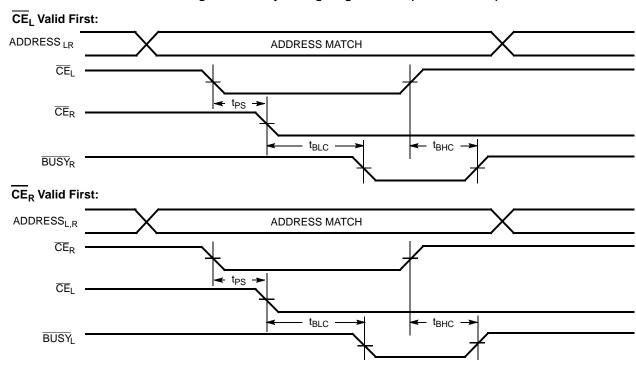
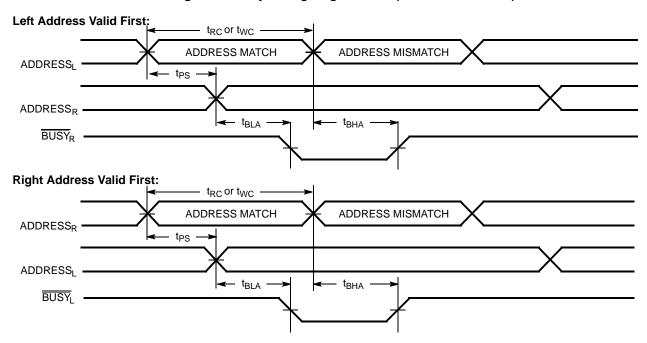


Figure 11. Busy Timing Diagram No. 2 (Address Arbitration)



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Figure 12. Busy Timing Diagram No. 3

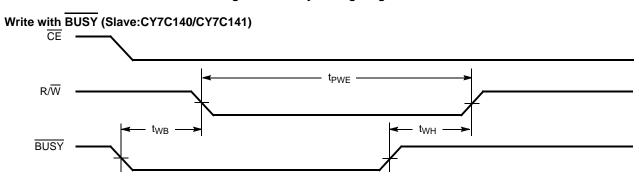
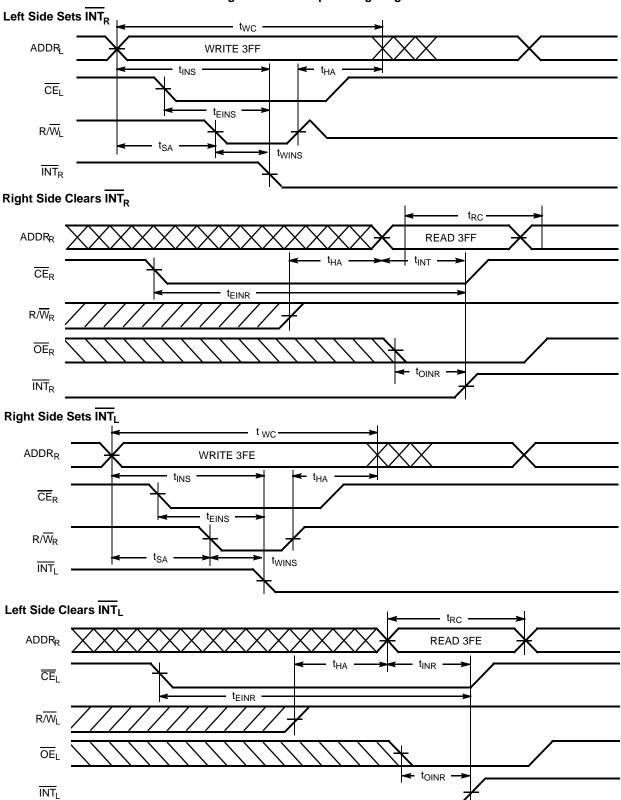


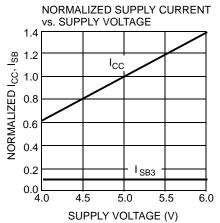


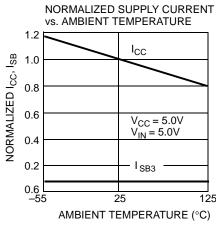
Figure 13. Interrupt Timing Diagrams

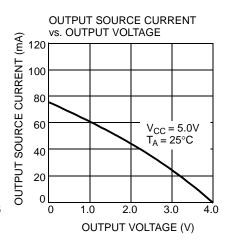


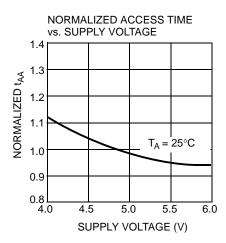


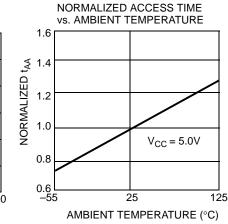
Typical DC and AC Characteristics

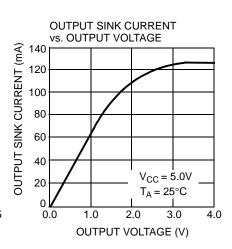


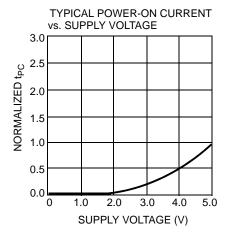


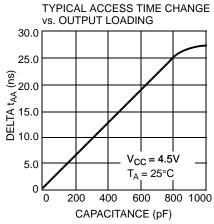


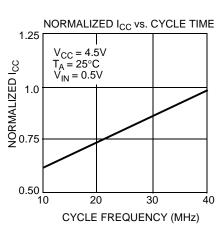














Ordering Information

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
30	CY7C130-30PC	P25	48-Pin (600 Mil) Molded DIP	Commercial
	CY7C130A-30PI	P25	48-Pin Pb-Free (600 Mil) Molded DIP	Industrial
35	CY7C130-35PC	P25	48-Pin (600 Mil) Molded DIP	Commercial
	CY7C130-35PI	P25	48-Pin (600 Mil) Molded DIP	Industrial
45	CY7C130-45PC	P25	48-Pin (600 Mil) Molded DIP	Commercial
	CY7C130-45PI	P25	48-Pin (600 Mil) Molded DIP	Industrial
55	CY7C130-55PC	P25	48-Pin (600 Mil) Molded DIP	Commercial
	CY7C130-55PI	P25	48-Pin (600 Mil) Molded DIP	Industrial
15	CY7C131-15JC	J69	52-Pin Plastic Leaded Chip Carrier	Commercial
	CY7C131-15JXC	J69	52-Pin Pb-Free Plastic Leaded Chip Carrier	
	CY7C131-15NC	N52	52-Pin Plastic Quad Flatpack	
	CY7C131-15JI	J69	52-Pin Plastic Leaded Chip Carrier	Industrial
	CY7C131A-15JXI	J69	52-Pin Pb-Free Plastic Leaded Chip Carrier	
	CY7C131-15NXI	N52	52-Pin Pb-Free Plastic Quad Flatpack	
25	CY7C131-25JC	J69	52-Pin Plastic Leaded Chip Carrier	Commercial
	CY7C131-25JXC	J69	52-Pin Pb-Free Plastic Leaded Chip Carrier	
	CY7C131-25NC	N52	52-Pin Plastic Quad Flatpack	
	CY7C131-25NXC	N52	52-Pin Pb-Free Plastic Quad Flatpack	
	CY7C131-25JI	J69	52-Pin Plastic Leaded Chip Carrier	Industrial
	CY7C131-25NI	N52	52-Pin Plastic Quad Flatpack	
30	CY7C131-30JC	J69	52-Pin Plastic Leaded Chip Carrier	Commercial
	CY7C131-30NC	N52	52-Pin Plastic Quad Flatpack	
	CY7C131-30JI	J69	52-Pin Plastic Leaded Chip Carrier	Industrial
35	CY7C131-35JC	J69	52-Pin Plastic Leaded Chip Carrier	Commercial
	CY7C131-35NC	N52	52-Pin Plastic Quad Flatpack	
	CY7C131-35JI	J69	52-Pin Plastic Leaded Chip Carrier	Industrial
	CY7C131-35NI	N52	52-Pin Plastic Quad Flatpack	
45	CY7C131-45JC	J69	52-Pin Plastic Leaded Chip Carrier	Commercial
	CY7C131-45NC	N52	52-Pin Plastic Quad Flatpack	
	CY7C131-45JI	J69	52-Pin Plastic Leaded Chip Carrier	Industrial
	CY7C131-45NI	N52	52-Pin Plastic Quad Flatpack	
55	CY7C131-55JC	J69	52-Pin Plastic Leaded Chip Carrier	Commercial
	CY7C131-55JXC	J69	52-Pin Pb-Free Plastic Leaded Chip Carrier	
	CY7C131-55NC	N52	52-Pin Plastic Quad Flatpack	
	CY7C131-55NXC	N52	52-Pin Pb-Free Plastic Quad Flatpack	
	CY7C131-55JI	J69	52-Pin Plastic Leaded Chip Carrier	Industrial
	CY7C131-55JXI	J69	52-Pin Pb-Free Plastic Leaded Chip Carrier	
	CY7C131-55NI	N52	52-Pin Plastic Quad Flatpack	
	CY7C131-55NXI	N52	52-Pin Pb-Free Plastic Quad Flatpack	
30	CY7C140-30PC	P25	48-Pin (600 Mil) Molded DIP	Commercial
	CY7C140-30PI	P25	48-Pin (600 Mil) Molded DIP	Industrial

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Ordering Information (continued)

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
35	CY7C140-35PC	P25	48-Pin (600 Mil) Molded DIP	Commercial
	CY7C140-35PI	P25	48-Pin (600 Mil) Molded DIP	Industrial
45	CY7C140-45PC	P25	48-Pin (600 Mil) Molded DIP	Commercial
	CY7C140-45PI	P25	48-Pin (600 Mil) Molded DIP	Industrial
55	CY7C140-55PC	P25	48-Pin (600 Mil) Molded DIP	Commercial
	CY7C140-55PI	P25	48-Pin (600 Mil) Molded DIP	Industrial
15	CY7C141-15JC	J69	52-Pin Plastic Leaded Chip Carrier	Commercial
	CY7C141-15NC	N52	52-Pin Plastic Quad Flatpack	
25	CY7C141-25JC	J69	52-Pin Plastic Leaded Chip Carrier	Commercial
	CY7C141-25JXC	J69	52-Pin Pb-Free Plastic Leaded Chip Carrier	
	CY7C141-25NC	N52	52-Pin Plastic Quad Flatpack	
	CY7C141-25JI	J69	52-Pin Plastic Leaded Chip Carrier	Industrial
	CY7C141-25NI	N52	52-Pin Plastic Quad Flatpack	
30	CY7C141-30JC	J69	52-Pin Plastic Leaded Chip Carrier	Commercial
	CY7C141-30NC	N52	52-Pin Plastic Quad Flatpack	
	CY7C141-30JI	J69	52-Pin Plastic Leaded Chip Carrier	Industrial
35	CY7C141-35JC	J69	52-Pin Plastic Leaded Chip Carrier	Commercial
	CY7C141-35NC	N52	52-Pin Plastic Quad Flatpack	
	CY7C141-35JI	J69	52-Pin Plastic Leaded Chip Carrier	Industrial
	CY7C141-35NI	N52	52-Pin Plastic Quad Flatpack	
45	CY7C141-45JC	J69	52-Pin Plastic Leaded Chip Carrier	Commercial
	CY7C141-45NC	N52	52-Pin Plastic Quad Flatpack	
	CY7C141-45JI	J69	52-Pin Plastic Leaded Chip Carrier	Industrial
	CY7C141-45NI	N52	52-Pin Plastic Quad Flatpack	
55	CY7C141-55JC	J69	52-Pin Plastic Leaded Chip Carrier	Commercial
	CY7C141-55NC	N52	52-Pin Plastic Quad Flatpack	
	CY7C141-55JI	J69	52-Pin Plastic Leaded Chip Carrier	Industrial
	CY7C141-55NI	N52	52-Pin Plastic Quad Flatpack	



Package Diagrams

Figure 14. 48-Pin (600 Mil) Sidebraze DIP D26

MIL-STD-1835 D-14 Config. C

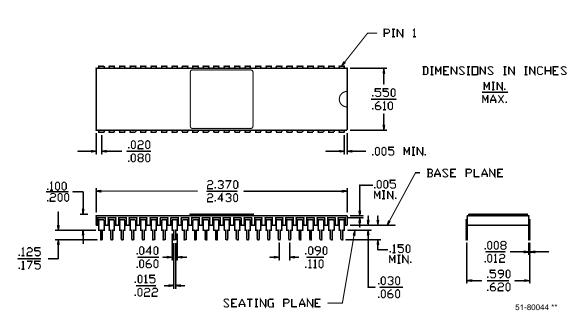
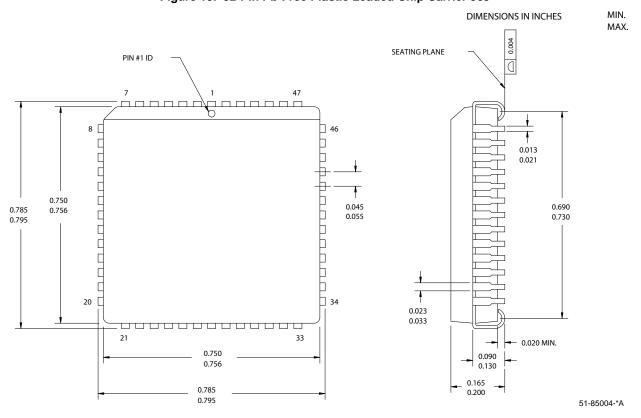


Figure 15. 52-Pin Pb-Free Plastic Leaded Chip Carrier J69





Package Diagrams (continued)

Figure 16. 48-Pin (600 Mil) Molded DIP P25

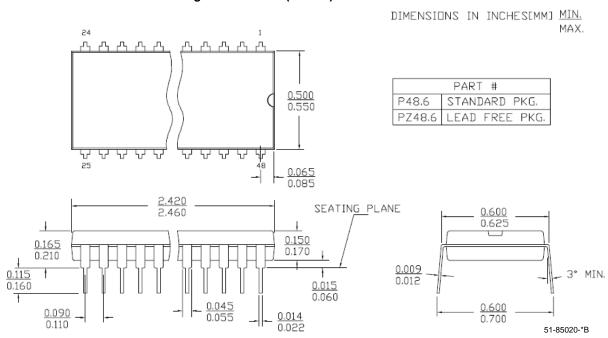
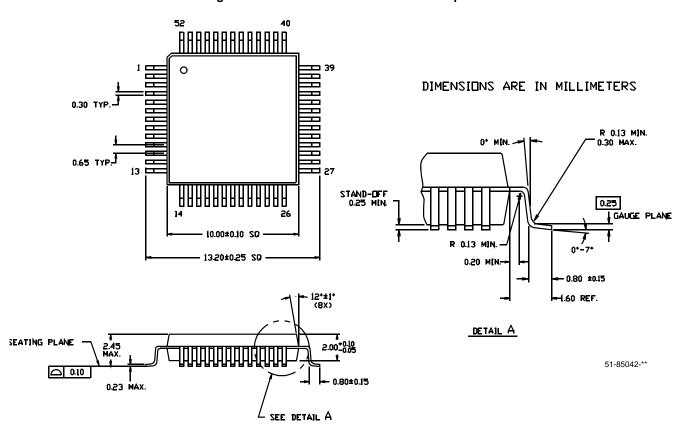


Figure 17. 52-Pin Pb-Free Plastic Quad Flatpack N52



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Document History Page

Rev.	ECN No.	Orig. of Change	Submission Date	Description of Change
**	110169	SZV	09/29/01	Change from Spec number: 38-00027 to 38-06002
*A	122255	RBI	12/26/02	Power up requirements added to Maximum Ratings Information
*B	236751	YDT	See ECN	Removed cross information from features section
*C	325936	RUY	See ECN	Added pin definitions table, 52-pin PQFP package diagram and Pb-free information
*D	393153	YIM	See ECN	Added CY7C131-15JI to ordering information Added Pb-Free parts to ordering information: CY7C131-15JXI
*E	2623540	VKN/PYRS	12/17/08	Added CY7C130A and CY7C131A parts Removed military information Updated ordering information table

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